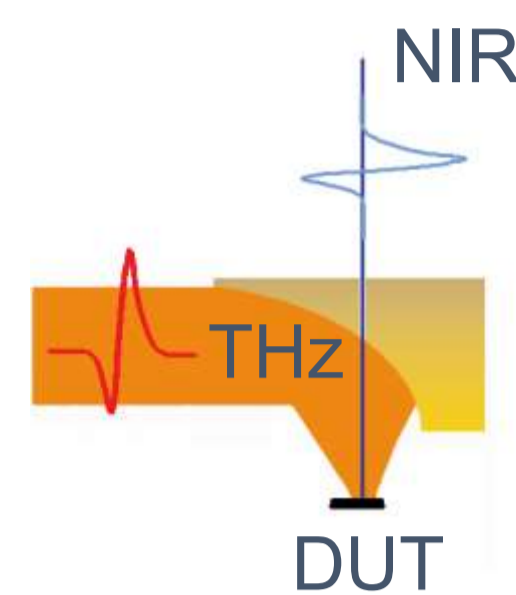


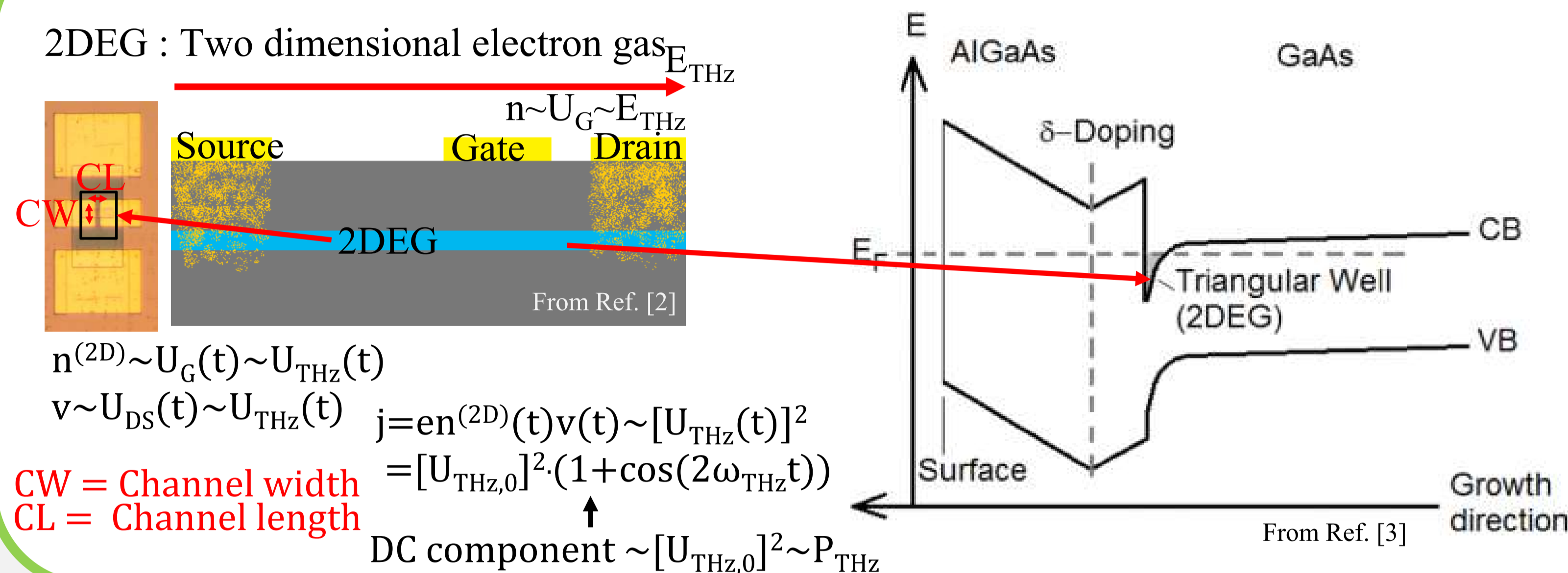
MOTIVATION

- Schottky diodes are faster, but break easily at higher power levels
- No direct locking between free electron laser (FEL) and near infrared (NIR) laser for pump and probe experiments
- Jitter and drift at picosecond scale while synchronizing the repetition rate between FEL and NIR laser
- Roll off at higher frequencies
- Precise on wafer de-embedding

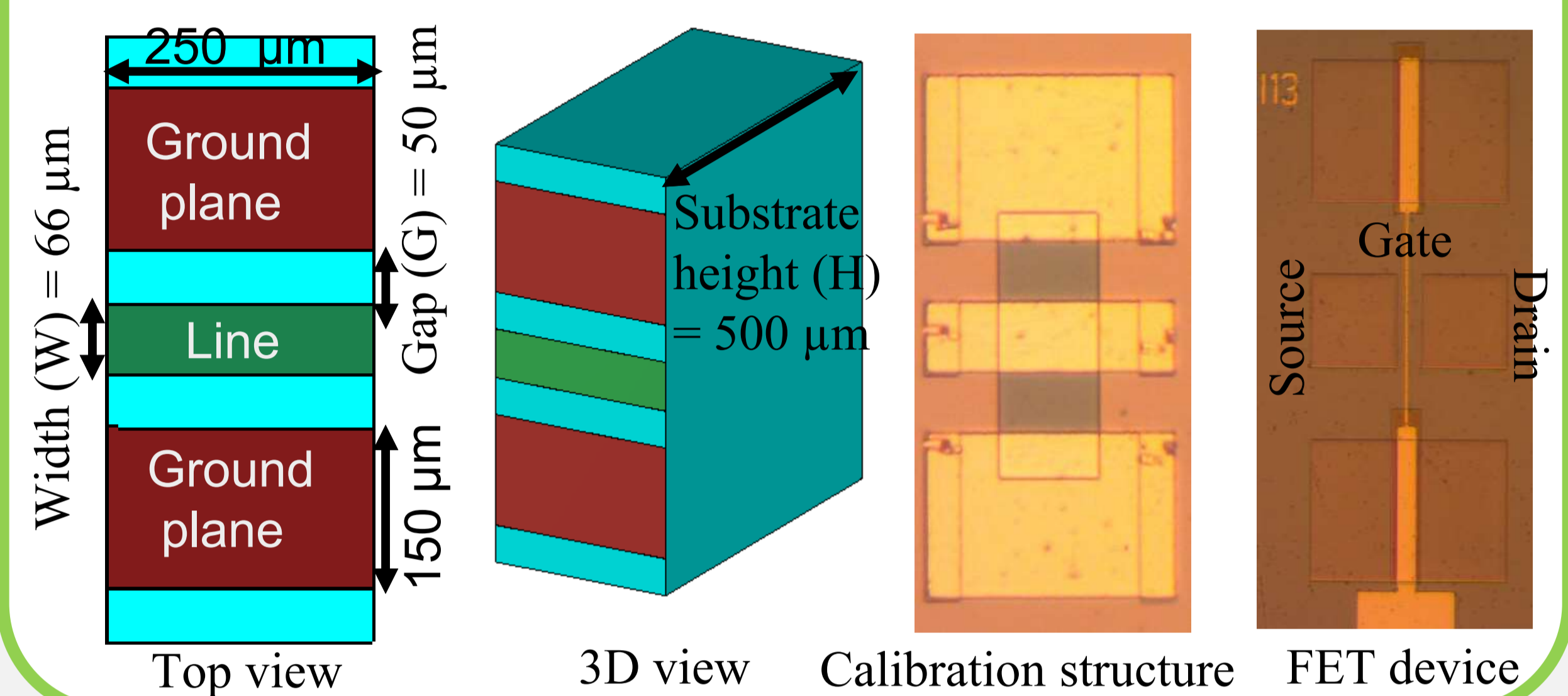


- GaAs based field effect transistor (FET) THz detectors:
 - Higher damage threshold compared to Schottky detectors
 - Higher mobility of GaAs compared to other substrates (e.g. GaN)
- Simultaneous detection of amplitude and timing at ps scale for THz and NIR pulses [1]
- Investigation of THz coupling in rectifying elements
- Antenna-coupled and large area FETs are promising candidates

THEORY OF THz DETECTION WITH FETs

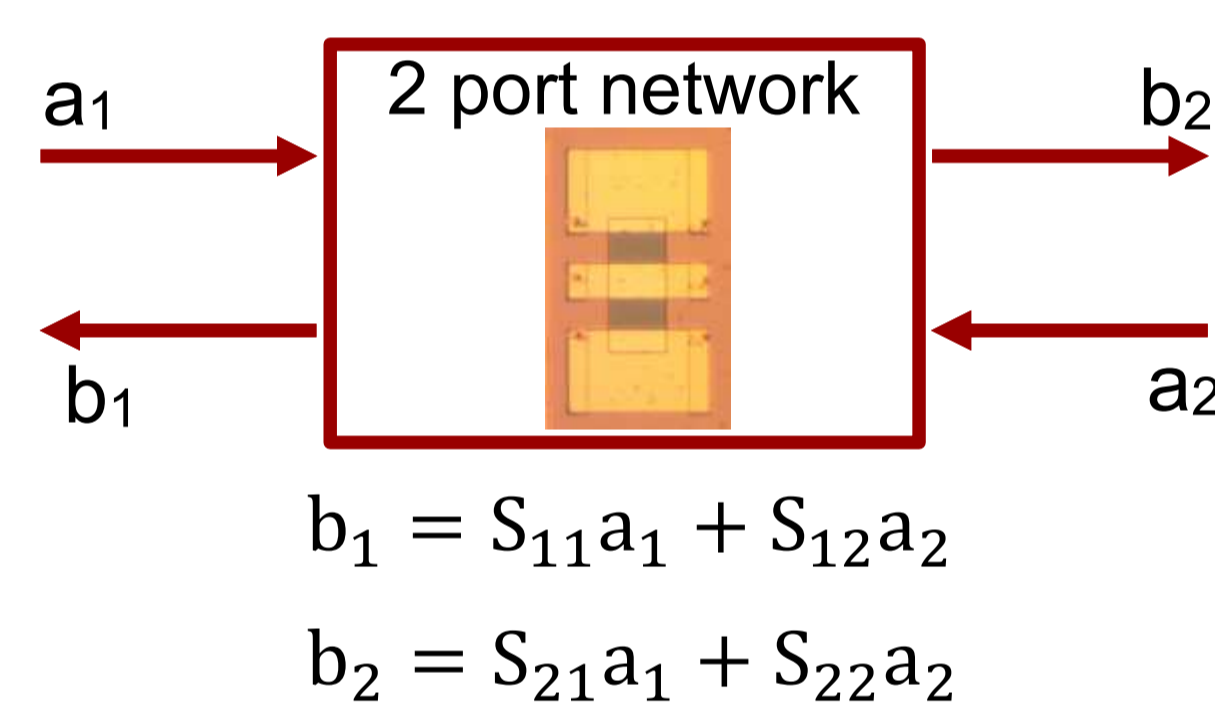
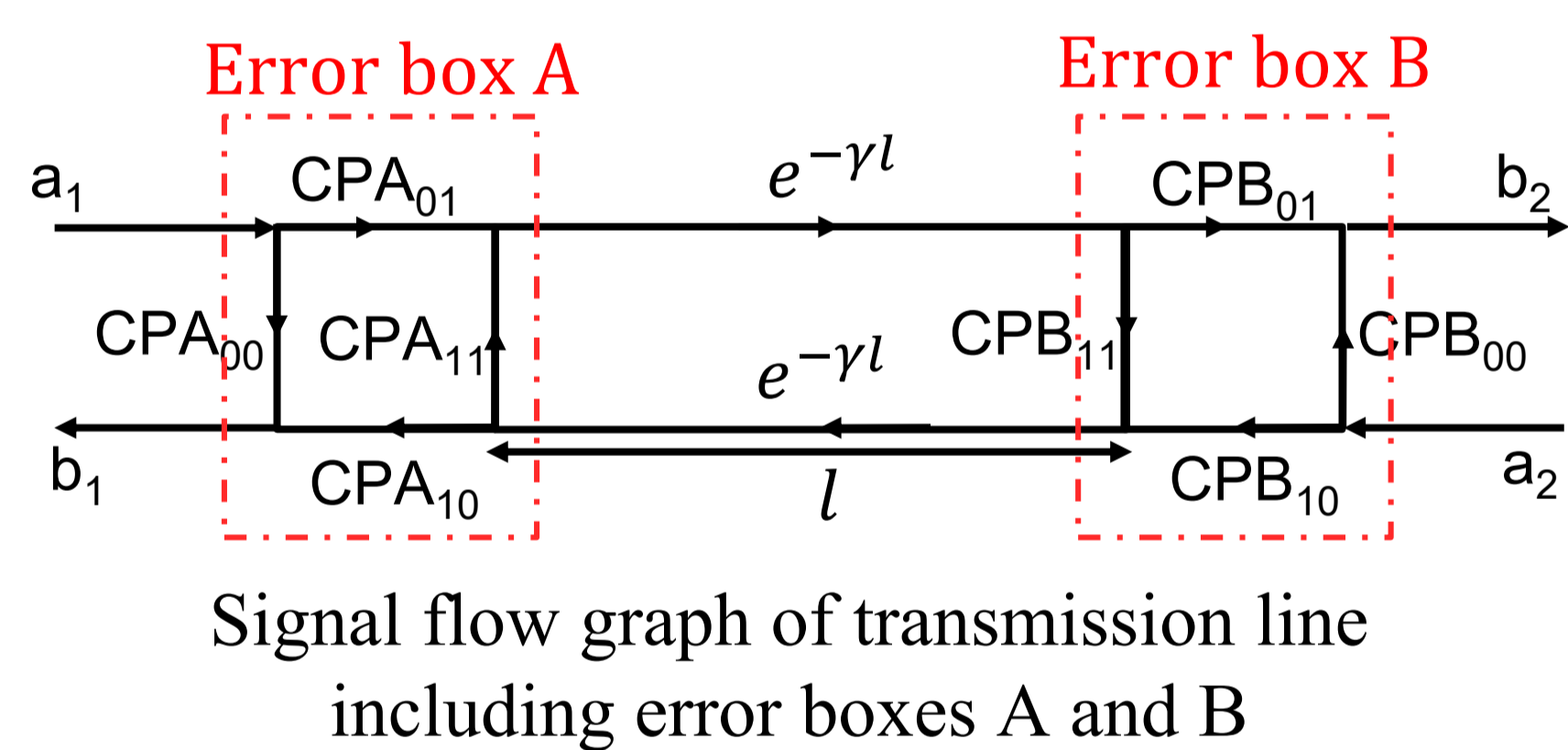


FABRICATED AND SIMULATED DEVICES



DEVICE CHARACTERIZATION BY S-PARAMETERS

- Transmission (S_{21}) and Reflection (S_{11}) coefficients
- Fast, simple, analytical and more accurate method for device characterization at higher frequencies
- Derivation of lumped elements of a transmission line



Lumped elements equivalent circuit of FETs

$$\frac{\partial U_{THz}}{\partial x} = -(r_0 + j\omega l_0)I_{THz}(x)$$

$$\frac{\partial I_{THz}}{\partial x} = -(g_0 + j\omega c_0)U_{THz}(x)$$

$$\gamma = \pm \sqrt{(r_0 + j\omega l_0)(g_0 + j\omega c_0)}$$

$$Z_{TL} = \sqrt{\frac{r_0 + j\omega l_0}{g_0 + j\omega c_0}}$$

γ = propagation constant

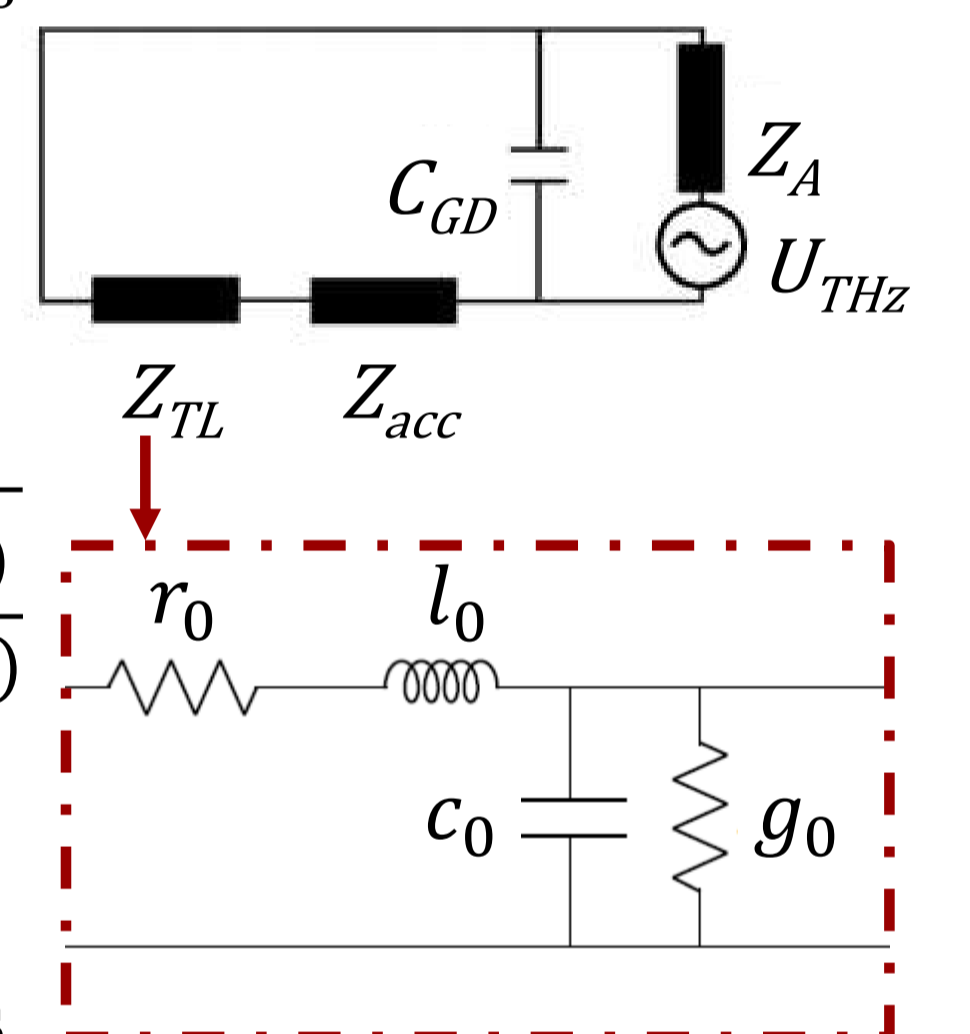
r_0 = resistance/length

g_0 = conductance/length

c_0 = capacitance/length

l_0 = inductance/length

Z_{TL} = Impedance of transmission line



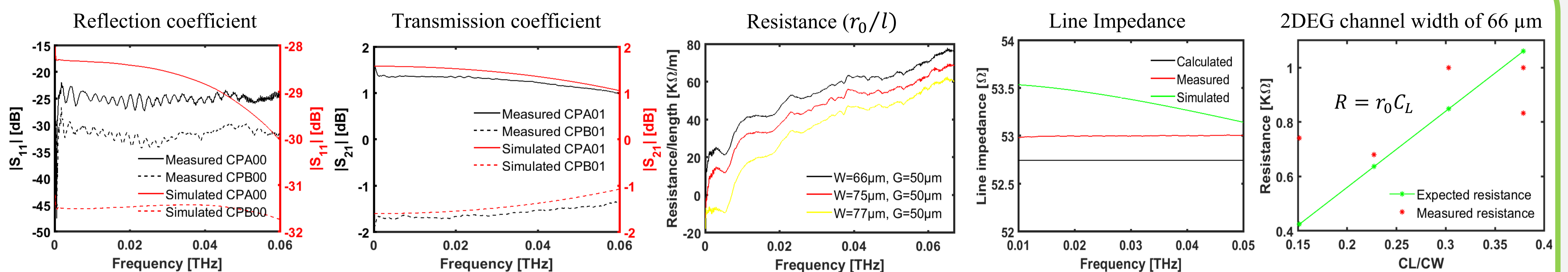
U_{THz} = THz bias

C_{GD} = Gate-Drain capacitance

Z_A = Antenna radiation impedance

Z_{acc} = Access impedance due to ungated part

RESULTS



On wafer TRL de-embedding and error boxes CPA and CPB calculation [5]

Derivation of r_0 for coplanar waveguide (CPW) with constant G and variable W

Good agreement between expected and measured values

CONCLUSION AND OUTLOOK

- Simulations fit to measurements
- On wafer TRL de-embedding performed successfully
- DC resistance of CL/CW is in agreement with expected values
- Value of lumped elements calculated for transmission line
- Lumped elements' values for 2DEG is under investigation
- Results will help in optimizing future FETs for accelerator applications

REFERENCES

- [1] Regensburger, Stefan, et al. "Broadband THz detection from 0.1 to 22 THz with large area field-effect transistors." *Optics express* 23.16 (2015): 20732-20742.
- [2] Preu, S., et al. "An improved model for non-resonant terahertz detection in field-effect transistors." *Journal of Applied Physics* 111.2 (2012): 024502.
- [3] Regensburger, Stefan, et al. "Broadband Terahertz Detection With Zero-Bias Field-Effect Transistors Between 100 GHz and 11.8 THz With a Noise Equivalent Power of 250 pW/ $\sqrt{\text{Hz}}$ at 0.6 THz." *IEEE Transactions on Terahertz Science and Technology* 8.4 (2018): 465-471.
- [4] Cascade microtech, user guide for 'On wafer VNA measurements.
- [5] Guoping, Tang, et al. "On-wafer de-embedding techniques from 0.1 to 110 GHz." *Journal of Semiconductors* 36.5 (2015): 054012.

ACKNOWLEDGMENT

This work is supported by the Hessen Ministry for Science & Arts and Technical University of Darmstadt